DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **PROBE** the specification of which is attached hereto unless the following is checked was filed on 19/05/2005 as United States Application Number or PCT International Application Number PCT/JP2005/009177 and was amended on (if applicable). I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above. I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56. I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) – (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed. **Priority Claimed** (List prior foreign applications. See Patent Application Japan 31/05/2004 note A) 2004-161844 (Number) (Country) (Day/Month/Year Filed) Yes □ No (Number) (Country) (Day/Month/Year Filed) Yes No (Number) (Country) (Day/Month/Year Filed) ☐ Yes ☐ No (Number) (Country) (Day/Month/Year Filed) (See note B) See attached list for additional prior foreign applications I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application. Status (List prior U.S. Applications) Patented Pending Abandoned (Filing Date) (Application Serial No.) Patented Pending Abandoned (Application Serial No.) (Filing Date) Patented Pending Abandoned (Application Serial No.) (Filing Date)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

 $23850 \\ \text{patent trademark office}$

Please direct all communications to the following address:

23850

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C)		irst inventor (given name, family name)	Kaz	umichi MACHIDA	
	Inventor's signature	hominicali Machial		29/9/2005	
	Residence	Takarazuka-shi, Japan	Citizenship	Japanese	
	Post Office Address	c/o Japan Electronic Materials Corporation, 2-5-13 Nishinagasu-cho Amagasaki-shi, Hyogo 660-0805, Japan			
	Full name of second i	nventor (given name, family name)	Atsuo URATA		
	Inventor's signature	Atsuo Urata	Date 2	9/9/2005	
	Residence	Ibaraki-shi, Japan	Citizenship	Japanese	
	Post Office Address	c/o Japan Electronic Materials Corporation, 2-5-13 Nishinagasu-cho Amagasaki-shi, Hyogo 660-0805, Japan			
	Full name of third inv	entor (given name, family name)	Т	akeshi KONNO	
	Inventor's signature	Takeshi Konno	Date	04/10/2005	
	Residence	Tsukuba-shi, Japan	Citizenship	Japanese	
	Post Office Address	c/o National Institute for Materials Science, 1-2-1, Sengen, Tsukuba-shi, Ibaraki			
		305-0047, Japan			
		nventor (given name, family name)		Akira ISHIDA	
	Inventor's signature	Akira Ishida	Date	05/10/2005	
	Residence	Tsukuba-shi, Japan	Citizenship	Japanese	
	Post Office Address	c/o National Institute for Materials Science	ence, 1-2-1, Sen	gen, Tsukuba-shi, Ibaraki	
		305-0047, Japan			
	Full name of fifth inv	entor (given name, family name)	Mi	tsuru EGASHIRA	
	Inventor's signature	william EgoShi	Date 05	-/10/2005	
	Residence	Tsukuba-shi, Japan	Citizenship	Japanese	
	Post Office Address	c/o National Institute for Materials Science, 1-2-1, Sengen, Tsukuba-shi, Ibaraki			
		305-0047, Japan			

Full name of sixth inv	ventor (given name, family name)	Mikihiko KOBAYASHI			
Inventor's signature	militaiho Kolmedi	Date 04	04/10/2005		
Residence	Ishioka-shi, Japan	Citizenship	Japanese		
Post Office Address	c/o National Institute for Materials S	Science, 1-2-1, Sengen,	Tsukuba, Ibaraki		
	305-0047, Japan				
-	inventor (given name, family name)				
Inventor's signature		Date	Date		
Residence		Citizenship			
Post Office Address					
Full name of eighth is	nventor (given name, family name)				
Inventor's signature		Date	Date		
Residence		Citizenship			
Post Office Address					

- .

NOTES

- A. Please list all foreign applications relating to the invention and check block, "yes" or "no".
- B. If more than 4 prior foreign applications, please check this box and attach a sheet listing the remaining prior foreign applications.
- C. For residence in the U.S., indicate <u>city and state</u>, for residence outside the U.S., indicate <u>city and country</u>. The "Post Office Address" must be an address acceptable by a Post Office for delivery of mail.